

1 74. The method as recited in claim 15, wherein the pad is a bumpless solder-
2 free pad.

1 75. The method as recited in claim 25, including attaching the substrate to the
2 chip using an adhesive that does not electrically connect the substrate and the chip.

1 76. The method as recited in claim 25, including attaching the substrate to the
2 chip using an adhesive that is sandwiched between and contacts the substrate and the chip
3 and does not electrically connect the substrate and the chip.

1 77. The method as recited in claim 25, wherein the pad is a bumpless pad.

1 78. The method as recited in claim 25, wherein the pad is a solder-free pad.

1 79. The method as recited in claim 25, wherein the pad is a bumpless solder-
2 free pad.

1 80. The method as recited in claim 50, including attaching the substrate to the
2 chip using an adhesive that does not electrically connect the substrate and the chip.

1 81. The method as recited in claim 50, including attaching the substrate to the
2 chip using an adhesive that is sandwiched between and contacts the substrate and the chip
3 and does not electrically connect the substrate and the chip.

1 82. The method as recited in claim 50, wherein the pad is a bumpless pad.

1 83. The method as recited in claim 50, wherein the pad is a solder-free pad.

1 84. The method as recited in claim 50, wherein the pad is a bumpless solder-
2 free pad.

1 85. The method as recited in claim 55, including attaching the substrate to the
2 chip using an adhesive that does not electrically connect the substrate and the chip.

1 86. The method as recited in claim 55, including attaching the substrate to the
2 chip using an adhesive that is sandwiched between and contacts the substrate and the chip
3 and does not electrically connect the substrate and the chip.

*Bl
contd*
1 87. The method as recited in claim 55, wherein the pad is a bumpless pad.

1 88. The method as recited in claim 55, wherein the pad is a solder-free pad.

1 89. The method as recited in claim 55, wherein the pad is a bumpless solder-
2 free pad.

1 90. The method as recited in claim 60, including attaching the substrate to the
2 chip using an adhesive that does not electrically connect the substrate and the chip.

1 91. The method as recited in claim 60, including attaching the substrate to the
2 chip using an adhesive that is sandwiched between and contacts the substrate and the chip
3 and does not electrically connect the substrate and the chip.

1 92. The method as recited in claim 60, wherein the pad is a bumpless pad.

1 93. The method as recited in claim 60, wherein the pad is a solder-free pad.

1 94. The method as recited in claim 60, wherein the pad is a bumpless solder-
2 free pad.